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(54) Title: **DISPERSION FOR CHEMICAL-MECHANICAL POLISHING**

(57) Abstract: An aqueous dispersion having a pH value of between 3 and 7 containing 1 to 35 wt.% of a pyrogenically produced silicon-aluminium mixed oxide powder with a specific surface area of 5 to 400 m<sup>2</sup>/g, wherein the proportion of aluminium oxide in the powder is between 90 and 99.9 wt.% or between 0.01 and 10 wt.%, the surface of the powder comprises zones of aluminium oxide and silicon dioxide and the powder exhibits no signals for crystalline silicon dioxide in an X-ray diffractogram. Said dispersion may be used for the chemical-mechanical polishing of conductive, metallic films.



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